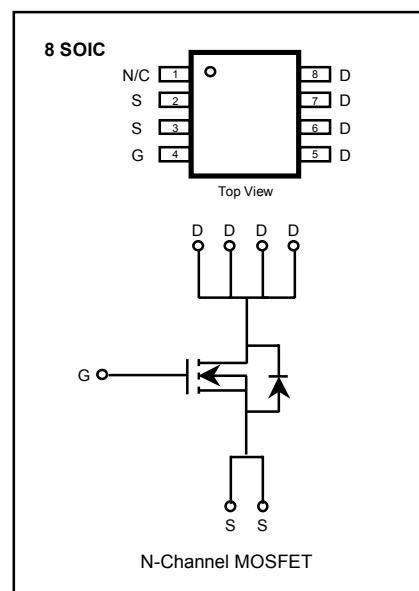


FEATURES

- Lower $R_{DS(ON)}$
- Improved Inductive Ruggedness
- Fast Switching Times
- Low Input Capacitance
- Extended Safe Operating Area
- Improved High Temperature Reliability



Product Summary

Part Number	BVdss	Rds(on)	I _D
SSD2101	30V	0.03Ω	7.0A

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V _{DSS}	Drain-to-Source Voltage	30	V
I _D	Continuous Drain Current T _A =25°C	7.0	A
	Continuous Drain Current T _A =70°C	5.8	
I _{DM}	Drain Current-Pulsed	20.0	A
V _{GS}	Gate-to-Source Voltage	±20	V
P _D	Total Power Dissipation (T _A =25°C)	2.5	W
	(T _A =70°C)	1.6	
T _J , T _{STG}	Operating and Junction Storage Temperature Range	- 55 to +150	°C

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
R _{θJA}	Junction-to-Ambient	--	50	°C/W

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	30	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	1.0	--	--	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$\text{V}_{\text{GS}}=20\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100	nA	$\text{V}_{\text{GS}}=-20\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	2.0	μA	$\text{V}_{\text{DS}}=24\text{V}$
		--	--	25		$\text{V}_{\text{DS}}=24\text{V}, \text{T}_C=55^\circ\text{C}$
I_{DON}	On-State Drain-Source Current	20	--	--	A	$\text{V}_{\text{DS}}=5\text{V}, \text{V}_{\text{GS}}=10\text{V}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance ⁽²⁾	--	--	0.03	Ω	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=7.0\text{A}$
		--	--	0.05		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=3.5\text{A}$
g_{fs}	Forward Transconductance ⁽²⁾	--	14	--	S	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_D=7.0\text{A}$
$t_{\text{d(on)}}$	Turn-On Delay Time	--	9.0	30	ns	$\text{V}_{\text{DD}}=25\text{V}, \text{I}_D=1.0\text{A}, \text{R}_0=6.0\Omega,$ ⁽²⁾⁽³⁾
t_r	Rise Time	--	18	60		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	79	150		
t_f	Fall Time	--	38	140		
Q_g	Total Gate Charge	--	35	50	nC	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_D=2.0\text{A}$ ⁽²⁾⁽³⁾
Q_{gs}	Gate-Source Charge	--	3.8	--		
Q_{gd}	Gate-Drain(" Miller ") Charge	--	7.4	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current (Body Diode)	--	--	2.8	A	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Rectifier
		--	--			
		--	--			
V_{SD}	Diode Forward Voltage ⁽²⁾	--	--	1.1	V	$\text{T}_A=25^\circ\text{C}, \text{I}_s=2.0\text{A}, \text{V}_{\text{GS}}=0\text{V}$
t_{rr}	Reverse Recovery Time ⁽²⁾	--	100	--	ns	$\text{T}_A=25^\circ\text{C}, \text{I}_F=2.0\text{A}, \text{di}_F/\text{dt}=100\text{A}/\mu\text{s}$

Notes :⁽¹⁾ Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature⁽²⁾ Pulse Test : Pulse Width = 250 μs , Duty Cycle $\leq 2\%$ ⁽³⁾ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

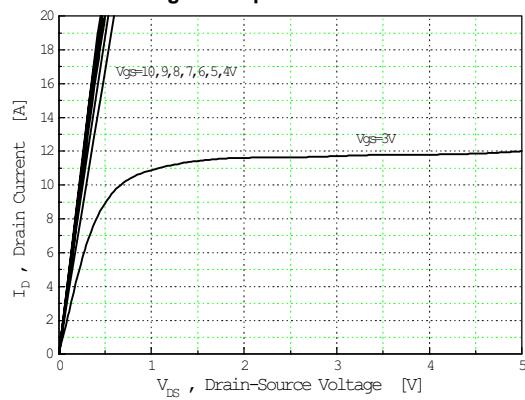


Fig 2. Transfer Characteristics

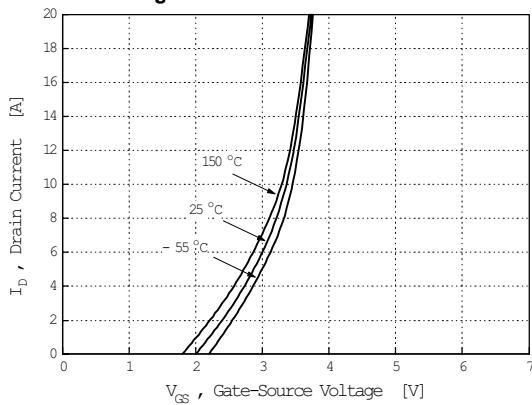


Fig 3. On-Resistance vs. Drain Current

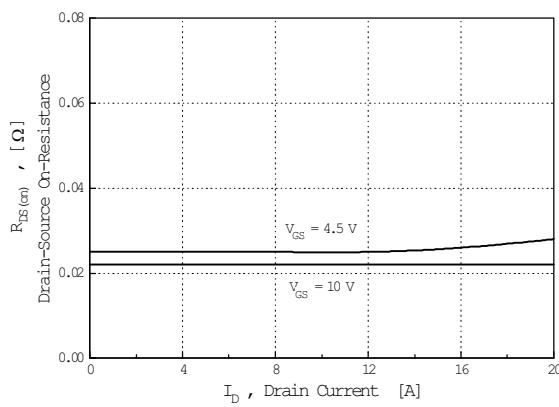


Fig 4. Source-Drain Forward Voltage

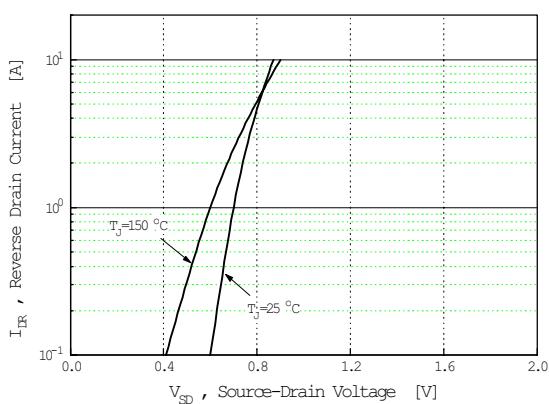


Fig 5. Capacitance vs. Drain-Source Voltage

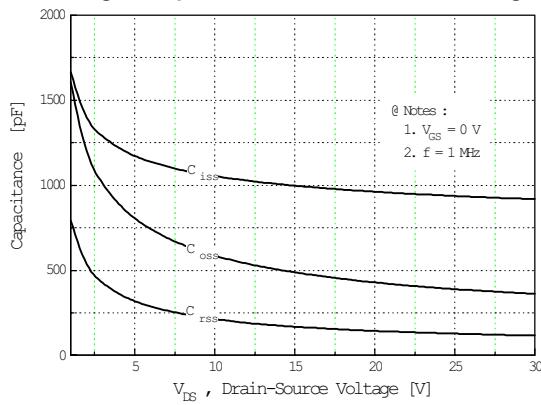


Fig 6. Gate Charge vs. Gate-Source Voltage

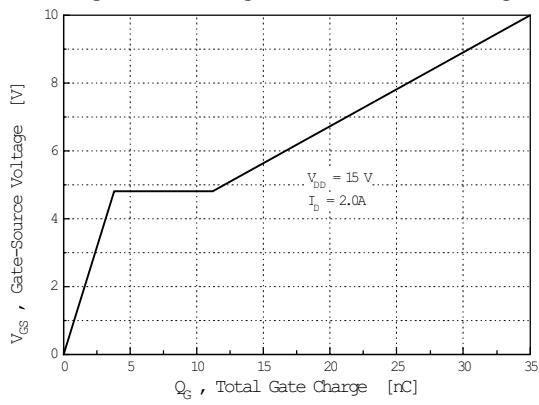


Fig 7. Breakdown Voltage vs. Temperature

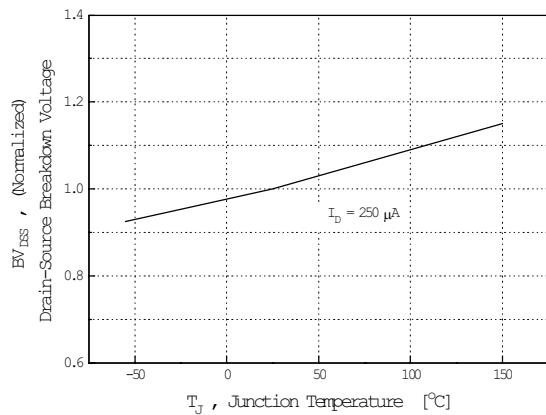


Fig 8. On-Resistance vs. Temperature

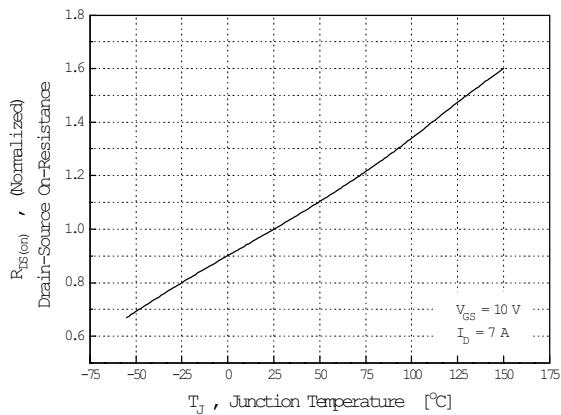


Fig 9. Normalized Effective Transient Thermal Impedance, Junction-to-Ambient

